## **INTEGRATED CIRCUITS**

## DATA SHEET

# **74F245**Octal transceiver (3-State)

Product specification

1994 Nov 15

IC15 Data Handbook

## **Philips Semiconductors**





74F245

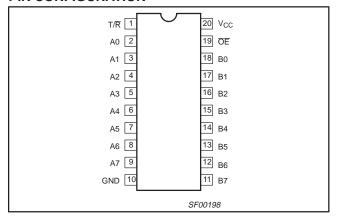
#### **FEATURES**

- Octal bidirectional bus interface
- 3-State buffer outputs sink 64mA
- 15mA source current
- Outputs are placed in high impedance state during power-off conditions

#### **DESCRIPTION**

The 74F245 is an octal transceiver featuring non-inverting 3-State bus compatible outputs in both transmit and receive directions. The B port outputs are capable of sinking 64mA and sourcing 15mA, producing very good capacitive drive characteristics. The device features an Output Enable  $(\overline{\text{OE}})$  input for easy cascading and Transmit/Receive (T/R) input for direction control. The 3-State outputs, B0–B7, have been designed to prevent output bus loading if the power is removed from the device.

#### **PIN CONFIGURATION**



TYPE	TYPICAL PROPAGATION DELAY	TYPICAL SUPPLY CURRENT (TOTAL)
74F245	4.0ns	70mA

#### ORDERING INFORMATION

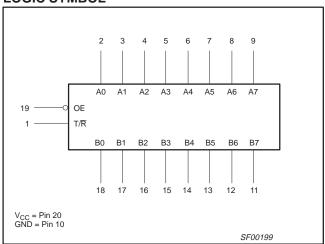
DESCRIPTION	COMMERCIAL RANGE V <sub>CC</sub> = 5V ±10%, T <sub>amb</sub> = 0°C to +70°C	DRAWING NUMBER
20-Pin Plastic DIP	N74F245N	SOT146-1
20-Pin Plastic SO	N74F245D	SOT163-1
20-Pin Plastic SSOP Type II	N74F245DB	SOT339-1

## INPUT AND OUTPUT LOADING AND FAN-OUT TABLE

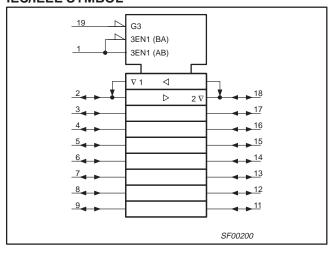
PINS	DESCRIPTION	74F (U.L.) HIGH/LOW	LOAD VALUE HIGH/LOW
A0-A7, B0-B7	Data inputs	3.5/1.0	70μA/0.6mA
ŌĒ	Output Enable input (active Low)	1.0/2.0	20μA/1.2mA
T/R	Transmit/Receive input	1.0/2.0	20μA/1.2mA
A0-A7	A port outputs	150/40	3.0mA/24mA
B0-B7	B port outputs	750/106.7	15mA/64mA

**NOTE:** One (1.0) FAST unit load is defined as: 20μA in the High state and 0.6mA in the Low state.

## **LOGIC SYMBOL**

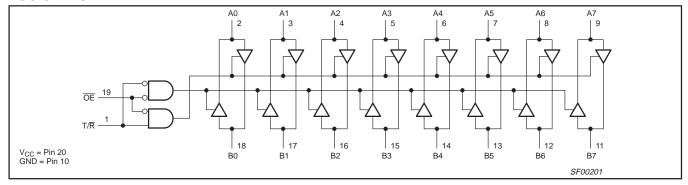


## **IEC/IEEE SYMBOL**



74F245

## **LOGIC DIAGRAM**



## **FUNCTION TABLE**

INP	JTS	OUTPUTS				
ŌĒ	T/R					
L	L	Bus B data to Bus A				
L	Н	Bus A data to Bus B				
Н	Х	Z				

H = High voltage level

L = Low voltage level

X = Don't care

Z = High impedance "off" state

## **ABSOLUTE MAXIMUM RATINGS**

(Operation beyond the limits set forth in this table may impair the useful life of the device. Unless otherwise noted these limits are over the operating free-air temperature range.)

SYMBOL	PARAMETER		RATING	UNIT		
V <sub>CC</sub>	Supply voltage		-0.5 to +7.0	V		
V <sub>IN</sub>	Input voltage	-0.5 to +7.0	V			
I <sub>IN</sub>	Input current	-30 to +5 m				
V <sub>OUT</sub>	Voltage applied to output in High output state	-0.5 to +5.5	V			
	Current applied to output in Lour output state	A0-A7	48	mA		
IOUT	Current applied to output in Low output state	B0-B7	128	mA		
T <sub>amb</sub>	Operating free-air temperature range		0 to +70	°C		
T <sub>stg</sub>	Storage temperature range	-65 to +150	°C			

## **RECOMMENDED OPERATING CONDITIONS**

CVMDOL	DADAMETED			LIMITS		LINUT
SYMBOL	PARAMETER		MIN	NOM	MAX	UNIT
V <sub>CC</sub>	Supply voltage		4.5	5.0	5.5	V
V <sub>IH</sub>	High-level input voltage		2.0			V
V <sub>IL</sub>	Low-level input voltage			0.8	V	
I <sub>IK</sub>	Input clamp current				-18	mA
	High-level output current	A0–A7			-3	mA
ГОН	nigh-lever output current	B0-B7			-15	mA
	Low level output ourrent	A0–A7			24	mA
I <sub>OL</sub>	Low-level output current	B0-B7			64	mA
T <sub>amb</sub>	Operating free-air temperature range		0		+70	°C

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#### DC ELECTRICAL CHARACTERISTICS

(Over recommended operating free-air temperature range unless otherwise noted.)

SYMBOL	PARAMETE	В	TEG	T CONDITIONS	21		LIMITS		UNIT
STWBUL	PARAMETE	ĸ	153	OI CONDITIONS	o'	MIN	TYP <sup>2</sup>	MAX	UNII
		40 47 50 57			±10% V <sub>CC</sub>	2.4			V
.,		A0–A7, B0–B7	$V_{CC} = MIN,$	$I_{OH} = -3mA$	±5% V <sub>CC</sub>	2.7	3.4		V
V <sub>OH</sub>	High-level output voltage	D0 D7	V <sub>IL</sub> = MAX, V <sub>IH</sub> = MIN		±10% V <sub>CC</sub>	2.0			V
		B0-B7		$I_{OH} = -15 \text{mA}$	±5% V <sub>CC</sub>	2.0			V
		40.47	V <sub>CC</sub> = MIN,	$I_{OL} = 20 \text{mA}$	±10% V <sub>CC</sub>		0.30	0.50	V
$V_{OL}$	Low-level output voltage	A0–A7	$V_{IL} = MAX$ ,	I <sub>OL</sub> = 24mA	±5% V <sub>CC</sub>		0.35	0.50	V
		B0-B7	V <sub>IH</sub> = MIN	I <sub>OL</sub> = MAX	±10% V <sub>CC</sub>			0.55	V
V <sub>OL</sub>	Low-level output voltage	B0–B7	$V_{CC} = MIN,$ $V_{IL} = MAX,$ $V_{IH} = MIN$	I <sub>OL</sub> = MAX	±5% V <sub>CC</sub>		0.42	0.55	V
V <sub>IK</sub>	Input clamp voltage	•	V <sub>CC</sub> = MIN, I <sub>I</sub> =	· I <sub>IK</sub>		-0.73	-1.2	V	
	Input current at maximum	ŌĒ, T/R	$V_{CC} = 5.5V, V_{I}$	= 7.0V			100	μΑ	
1 <sub>1</sub>	input voltage	A0-A7, B0-B7	$V_{CC} = 5.5V, V_I$	= 5.5V			1	mA	
I <sub>IH</sub>	High-level input current	OE, T/R only	$V_{CC} = MAX, V_I$	= 2.7V				20	μΑ
I <sub>IL</sub>	Low-level input current	OE, T/R only	$V_{CC} = MAX, V_I$	= 0.5V				-1.2	mA
I <sub>IH</sub> +I <sub>OZH</sub>	Off-state output current High level voltage applied		V <sub>CC</sub> = MAX, V <sub>0</sub>	<sub>O</sub> = 2.7V				70	μΑ
I <sub>IL</sub> +I <sub>OZL</sub>	Off-state output current Low level voltage applied		V <sub>CC</sub> = MAX, V <sub>0</sub>	<sub>O</sub> = 0.5V				-600	μА
	Object simulification of summer 13	A0-A7	\/ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \			-60		-150	mA
los	Short-circuit output current <sup>3</sup>	B0-B7	$V_{CC} = MAX$			-100		-225	mA
		Іссн					60	87	mA
I <sub>CC</sub>	Supply current (total)	I <sub>CCL</sub>	$V_{CC} = MAX$			70	100	mA	
		I <sub>CCZ</sub>	1			75	110	mA	

## **AC ELECTRICAL CHARACTERISTICS**

				LIMITS							
SYMBOL	PARAMETER	TEST CONDITION	V <sub>0</sub> T <sub>ai</sub> C <sub>L</sub> = 5	<sub>CC</sub> = +5.0 <sub>mb</sub> = +25 0pF, R <sub>L</sub> =	V °C : 500Ω	V <sub>CC</sub> = +5. T <sub>amb</sub> = 0°C C <sub>L</sub> = 50pF,	UNIT				
			MIN	TYP	MAX	MIN	MAX	l			
t <sub>PLH</sub> t <sub>PHL</sub>	Propagation delay An to Bn, Bn to An	Waveform 1	2.5 2.5	3.5 4.0	6.0 6.0	2.5 2.5	7.0 7.0	ns			
t <sub>PZH</sub> t <sub>PZL</sub>	Output Enable time to High or Low level	Waveform 2 Waveform 3	2.0 3.5	4.5 5.5	7.0 8.0	2.0 3.5	8.0 9.0	ns			
t <sub>PHZ</sub> t <sub>PLZ</sub>	Output Disable time from High or Low level	Waveform 2 Waveform 3	2.5 1.0	5.0 3.5	6.5 6.0	2.0 1.0	7.5 7.0	ns			

For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions for the applicable type.
 All typical values are at V<sub>CC</sub> = 5V, T<sub>amb</sub> = 25°C.
 Not more than one output should be shorted at a time. For testing I<sub>OS</sub>, the use of high-speed test apparatus and/or sample-and-hold techniques are preferable in order to minimize internal heating and more accurately reflect operational values. Otherwise, prolonged shorting of a High output may raise the chip temperature well above normal and thereby cause invalid readings in other parameter tests. In any sequence of parameter tests, I<sub>OS</sub> tests should be performed last.

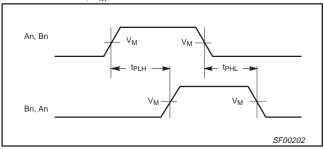
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## Octal transceiver (3-State)

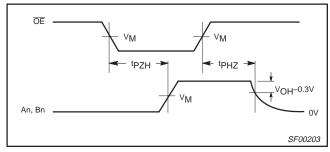
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#### **AC WAVEFORMS**

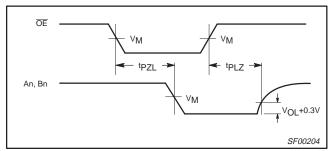
For all waveforms,  $V_M = 1.5V$ .



Waveform 1. Propagation Delay for Non-Inverting Output

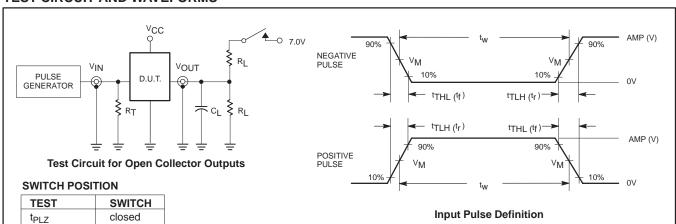


Waveform 2. 3-State Output Enable Time to High Level and Output Disable Time from High Level



Waveform 3. 3-State Output Enable Time to Low Level and Output Disable Time from Low Level

## **TEST CIRCUIT AND WAVEFORMS**



## All other

 $t_{PZL}$ 

**DEFINITIONS:** R<sub>L</sub> = Load resistor;

see AC electrical characteristics for value.

closed

open

C<sub>L</sub> = Load capacitance includes jig and probe capacitance; see AC electrical characteristics for value.

R<sub>T</sub> = Termination resistance should be equal to Z<sub>OUT</sub> of pulse generators.

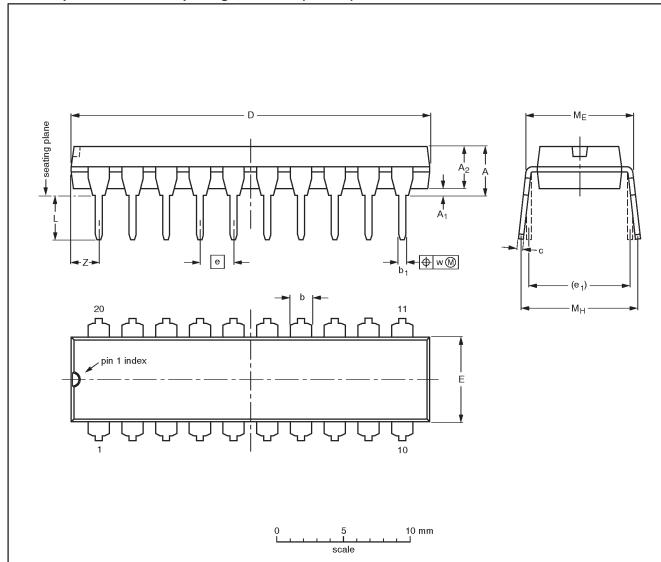
family	INP	INPUT PULSE REQUIREMENTS												
family	amplitude	$V_{\text{M}}$	rep. rate	t <sub>w</sub>	t <sub>TLH</sub>	t <sub>THL</sub>								
74F	3.0V	1.5V	1MHz	500ns	2.5ns	2.5ns								

SF00128

74F245

## DIP20: plastic dual in-line package; 20 leads (300 mil)

SOT146-1



## DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub> min.	A <sub>2</sub> max.	b	b <sub>1</sub>	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	e <sub>1</sub>	L	ME	Мн	w	Z <sup>(1)</sup> max.
mm	4.2	0.51	3.2	1.73 1.30	0.53 0.38	0.36 0.23	26.92 26.54	6.40 6.22	2.54	7.62	3.60 3.05	8.25 7.80	10.0 8.3	0.254	2.0
inches	0.17	0.020	0.13	0.068 0.051	0.021 0.015	0.014 0.009	1.060 1.045	0.25 0.24	0.10	0.30	0.14 0.12	0.32 0.31	0.39 0.33	0.01	0.078

#### Note

1. Plastic or metal protrusions of 0.25 mm maximum per side are not included.

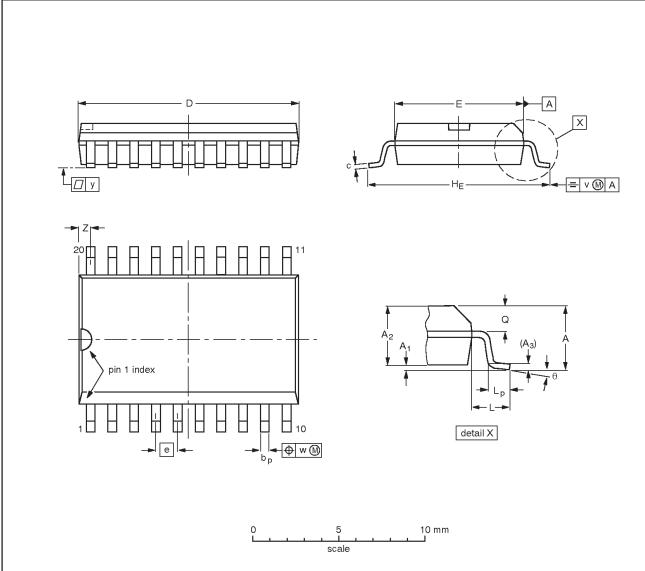
OUTLINE		REFER	EUROPEAN	ISSUE DATE				
VERSION	VERSION IEC JEDEC		EIAJ		PROJECTION	ISSUE DATE		
SOT146-1			SC603			<del>92-11-17</del> 95-05-24		

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## SO20: plastic small outline package; 20 leads; body width 7.5 mm

SOT163-1



## DIMENSIONS (inch dimensions are derived from the original mm dimensions)

UNIT	A max.	A <sub>1</sub>	A <sub>2</sub>	А3	bр	С	D <sup>(1)</sup>	E <sup>(1)</sup>	е	HE	L	Lp	Q	v	w	у	z <sup>(1)</sup>	θ
mm	2.65	0.30 0.10	2.45 2.25	0.25	0.49 0.36	0.32 0.23	13.0 12.6	7.6 7.4	1.27	10.65 10.00	1.4	1.1 0.4	1.1 1.0	0.25	0.25	0.1	0.9 0.4	8°
inches	0.10	0.012 0.004	0.096 0.089	0.01	0.019 0.014	0.013 0.009	0.51 0.49	0.30 0.29	0.050	0.419 0.394	0.055	0.043 0.016		0.01	0.01	0.004	0.035 0.016	0°

#### Note

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.

OUTLINE		REFER	EUROPEAN	ISSUE DATE			
VERSION	IEC	JEDEC	EIAJ		PROJECTION	ISSUE DATE	
SOT163-1	075E04	MS-013AC				<del>-95-01-24</del> 97-05-22	

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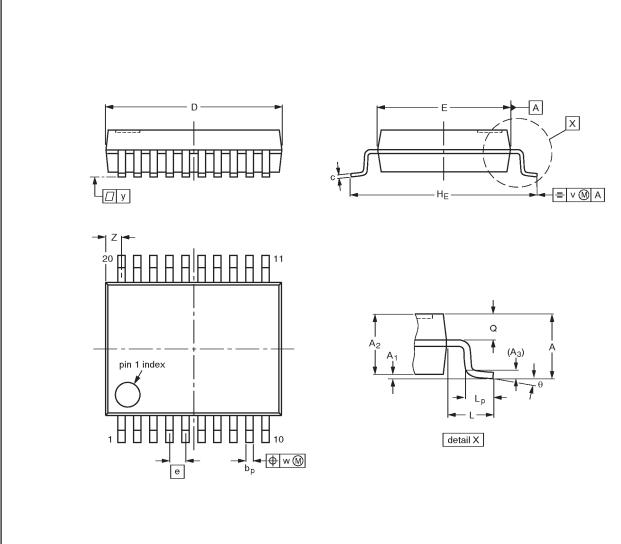
**NOTES** 

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## SSOP20: plastic shrink small outline package; 20 leads; body width 5.3 mm

SOT339-1



## 

## DIMENSIONS (mm are the original dimensions)

UNIT	A max.	Α1	A <sub>2</sub>	А3	р <sub>р</sub>	O	D <sup>(1)</sup>	E <sup>(1)</sup>	Ф	HE	L	Lp	œ	v	w	у	Z <sup>(1)</sup>	θ
mm	2.0	0.21 0.05	1.80 1.65	0.25	0.38 0.25	0.20 0.09	7.4 7.0	5.4 5.2	0.65	7.9 7.6	1.25	1.03 0.63	0.9 0.7	0.2	0.13	0.1	0.9 0.5	8° 0°

#### Note

1. Plastic or metal protrusions of 0.20 mm maximum per side are not included.

OUTLINE VERSION		REFER	EUROPEAN	ISSUE DATE		
	IEC	JEDEC	EIAJ		PROJECTION	ISSUEDATE
SOT339-1		MO-150AE				<del>93-09-08</del> 95-02-04

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Data Sheet Identification	Product Status	Definition				
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Product Specification	Full Production	This data sheet contains Final Specifications. Philips Semiconductors reserves the right to make changes at any time without notice, in order to improve design and supply the best possible product.				

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